

PCN Number:	20160607002		PCN Date:	6/10/2016															
Title:	Qualification of new Assembly & Test site (TI Taiwan) & New material set for the UCCx895DW Device family																		
Customer Contact:	PCN Manager	Dept:	Quality Services																
Proposed 1st Ship Date:	9/10/2016	Estimated Sample Availability:	Provided upon Request																
Change Type:																			
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials														
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification														
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process														
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process														
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process														
		<input type="checkbox"/>	Part number change																
PCN Details																			
Description of Change:																			
Texas Instruments is pleased to announce the qualification TI Taiwan as an additional Assembly & Test site for the UCCx895DW Device family with BOM differences noted below:																			
<table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>What</th> <th>Carsem</th> <th>TI Taiwan</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>SID#434165</td> <td>4147858</td> </tr> <tr> <td>Mold Compound</td> <td>SID#438359</td> <td>4211880</td> </tr> <tr> <td>Bond Wire</td> <td>Au, 1.3 mils</td> <td>Cu, 0.96 mils</td> </tr> <tr> <td>Leadframe</td> <td>Standard</td> <td>Roughened</td> </tr> </tbody> </table>					What	Carsem	TI Taiwan	Mount Compound	SID#434165	4147858	Mold Compound	SID#438359	4211880	Bond Wire	Au, 1.3 mils	Cu, 0.96 mils	Leadframe	Standard	Roughened
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Bond Wire	Au, 1.3 mils	Cu, 0.96 mils																	
Leadframe	Standard	Roughened																	
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																			
Reason for Change:																			
Continuity of Supply																			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																			
None																			
Anticipated impact on Material Declaration																			
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .																
Changes to product identification resulting from this PCN:																			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City																
Carsem	CAR	MYS	Ipoh																
TI Taiwan	TAI	TWN	Chung Ho, New Taipei City																
Sample product shipping label (not actual product label)																			



MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Topside Device marking (if included):

Assembly site code for CAR= V

Assembly site code for TAI = T

Product Affected

UCC2895DW	UCC2895DWTR	UCC3895DW	UCC3895DWTR
UCC2895DWG4	UCC2895DWTRG4	UCC3895DWG4	UCC3895DWTRG4



TI Information
Selective Disclosure

Qualification Report

UCC3895DWTR Assembly and Test Offload to TITL with Copper Wire

Product Attributes

Attributes	Qual Device: UCC3895DWTR	QBS Package Reference: ADS820U_QMI505MT_CU_SSTN	QBS Package Reference: ADS8504IBDW_QMI505MT_CU_STD	QBS Package Reference: TPS2101D	QBS Package Reference: TSS721AD	QBS Package Reference: ULQ2003AQRQ1_STDLF
Assembly Site	TAI	TAI	TAI	TAI	TAI	FMX
Package Family	SOIC WIDE	SOIC	SOIC	SOIC	SOIC	SOIC
Flammability Rating	-	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	TSMC WF2	DMOS5	DFAB	SFAB	SFAB
Wafer Fab Process	IMP-PWR2	0.60UM-TSMC	50HPA07	LBC3S	J11	J11-SLM

- QBS: Qual By Similarity

- Qual Device UCC3895DWTR is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC3895DWTR	QBS Package Reference: ADS820U_QMI505MT_CU_SSTN	QBS Package Reference: ADS8504IBDW_QMI505MT_CU_STD	QBS Package Reference: TPS2101D	QBS Package Reference: TSS721AD	QBS Package Reference: ULQ2003AQRQ1_STDLF
AC	Autoclave 121C	96 Hours	-	-	1/77/0	-	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	3/231/0
HTOL	Life Test, 150C	408 Hours	-	-	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	-	1/45/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	1/77/0	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0
WBP	Bond Pull	Wires	Pass	-	-	-	-	-
WBS	Ball Bond Shear	Wires	Pass	-	-	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com